

## Product Information Sheet

**MATERIAL ID:**

**EPO-TEK® OG115**

**Date:** 08/2007

**Per:**

**Rev:** II

**Material Description:**

A single component, UV curable epoxy, designed for adhesive, sealing, and encapsulating applications found in semiconductor, electro-optics, fiber optics, medical, and scientific/OEM industries. It is an ideal all-purpose adhesive.

**Number of Components:**

Single

**Mix Ratio by weight:**

N/A

**Cure Schedule (minimum)\***

100mW/cm<sup>2</sup> for 2 minutes @ 320-500 nm (depending on thickness)

**Specific Gravity:**

1.20 --- Part A: Part B:

**Pot Life:**

N/A

**Shelf Life:**

One year at room temperature

*NOTE:* Container(s) should be kept closed in a dark location when not in use.

\*Please see Applications Note(s) available on our website.

**MATERIAL CHARACTERISTICS:** *To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.*

\* denotes test on lot acceptance basis; Cure condition: varies as required

<b>PHYSICAL PROPERTIES:</b>	
* <b>Color (before cure):</b>	Clear/Colorless
* <b>Consistency:</b>	Pourable liquid
* <b>Viscosity (23°C):</b>	
@ 100 rpm	800 - 1200 cPs
<b>Thixotropic Index:</b>	N/A
* <b>Glass Transition</b>	≥ 90 °C (Post-Cure)
	Dynamic Scan 20—200°C; Ramp -10—200°C @ 20°C/Min)
<b>Coefficient of Thermal Expansion (CTE):</b>	
Below Tg:	68 x 10 <sup>-6</sup> in/in°C
Above Tg:	223 x 10 <sup>-6</sup> in/in°C
<b>Shore D Hardness:</b>	85
<b>Die Shear @ 23°C:</b>	≥ 5 Kg / 1,700 psi
<b>Degradation Temp:</b>	360 °C
<b>Weight Loss:</b>	
@ 200°C:	1.02 %
@ 250°C:	2.29 %
@ 300°C:	5.78 %
<b>Operating Temp:</b>	
Continuous:	- 55°C to + 200°C
Intermittent:	- 55°C to + 300°C
<b>Storage Modulus @ 23°C:</b>	268,482 psi
* <b>Particle Size:</b>	N/A

<b>OPTICAL PROPERTIES @ 23°C:</b>	
<b>Spectral Transmission:</b>	> 94 % @ 1600 nm
	> 95 % @ 900 nm
	> 92 % @ 600 nm
<b>Refractive Index (uncured):</b>	1.5567 @ 589 nm